

The image displays the top and bottom views of the PCB. The top view shows a complex layout with various components labeled, including resistors (R1, R2), capacitors (C1, C2, C3, C4, C5), diodes (D1, D2, D3, D4, D5), and integrated circuits (U1, U2, U3, U4, U5, U6). The bottom view shows the reverse side of the board, which is mostly black with some yellow components visible.

PCB Size	22 mm x 70 mm	Customer Panel Size	<div></div>
PCB Thickness	1.6 mm	Max. Aspect Ratio on PTH	0.8
Copper Layers	2	Pressing Stages	1
Surface Finish	unknown	Drill Hole Density	58 Holes/dm ²
Solder Mask	Both	Testable Points	84
Solder Mask Color	Green	Min. SMD/BGA Size	0.48 mm
Legend	Top Only	!HolesInPadPth!	No
Legend Color	White	!HolesInPadBlind!	No
Edge Connector Area	0 dm ²	Stacked Vias	<div></div>
Peeloff Mask	No	Castellated	No
Carbon Mask	No	Anomalies	No

Type	Copper Width	Critical Copper Width	Trace Width	Critical Trace Width	Copper to Copper Clr.	Trace to Trace Clr.	Same Net Clr.	Ring	Copper to Outline Clr.
	mm	mm	mm	mm	mm	mm	mm	mm	mm
Outer	¹ 0.250	² 0.250	³ 0.250	⁴ 0.250	⁵ 0.235	⁶ 0.341	⁷ 0.380	⁸ 0.150	⁹ 0.314

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Summary - Copper Layer Minima - Original

Type	Copper to Plated Clr.				Copper to NPTH Clr.			
	!Min.Clr.Overall! mm	!Min.Clr.toPad! mm	!Min.Clr.toTrace! mm	!Min.Clr.toRegion! mm	!Min.Clr.Overall! mm	!Min.Clr.toPad! mm	!Min.Clr.toTrace! mm	!Min.Clr.toRegion! mm
Outer	¹⁰ 0.447	¹¹ 0.459	¹² 0.447	>0.800				
Inner								

Summary - Sequences - Original


Type	Sequences	Tools	Min. End Dia. mm	Max. End Dia. mm	Holes	Routs	Ring on Outer mm	Ring on Inner mm	Hole to Copper Clr. mm
PTH	1	3	2.000	2.700	9	0	0.150		0.447
Total	1	3	2.000	2.700	9	0	0.150		0.447

Summary - Rout - Original

Type	Tools	Min. End Dia. mm	Max. End Dia. mm	Rout Length mm
Plated				
NPTH				
Total				

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Stackup - Original

	
Pressing Stages	1

Files - Original

Initial	Renamed	Function	Position	Color	Thickness	
					Base	Finished
					mm	mm
stencil-top.pho	paste-top	paste	top			
silkscreen-top.pho	silk-top	silk	top	white	unknown	unknown
solder-mask-top.pho	mask-top	mask	top	black	unknown	unknown
copper-top.pho	top	outer	1		0.035	unknown
copper-bottom.pho	bot	outer	2		0.035	unknown
solder-mask-bottom.pho	mask-bot	mask	bottom	black	unknown	unknown
drill-npth.pho	pth_1	plated	1-2			
drill.pho	pth	plated	1-2			
outline.pho	outline	cad_outline	none			
silkscreen-bottom.pho	silkscreen-bottom_pho	empty	none			
stencil-bottom.pho	stencil-bottom_pho	empty	none			

PCB (Single) - Original

PCB Size	Outline Type	Outline Length	Outline Area	Copper Layers	PCB Thickness
mm x mm		mm	dm ²		mm
22.000 x 70.000	real	184.000	0.1540	2	1.600

Customer Panel (Delivery Array, Assembly Panel) - Original

Original Image	Panel Size	Left	Right	Top	Bottom	X Spacing	Y Spacing	PCB's	Depanel Rout Length
	mm x mm	mm	mm	mm	mm	mm	mm		mm

Thickness - Original

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Copper Layer Minima & Area - Original

File	Pos.	Copper Width	Critical Copper Width	Trace Width	Critical Trace Width	Copper to Copper Clr.	Same Net Clr.	Copper Area	
		mm	mm	mm	mm	mm	mm	dm ²	%
top	1	0.250	0.250	0.250	0.250	0.235	0.380	0.0897	58
bot	2	>0.400	>0.400	>0.400	>0.400	0.450	>0.500	0.0081	5

Copper Layer Minima - Copper to Drill Minima - Original

File	Pos.	Ring					Copper to Drill Clr.		Copper to Outline Clr.			
		Overall	Via	Laser Via	Comp.	Mech.	Plated	NPTH	Overall	to Pad	to Trace	to Region
		mm	mm	mm	mm	mm	mm	mm	mm	mm	mm	mm
top	1	0.150			0.150		0.447		0.314	0.314	1.243	1.054
bot	2	0.150			0.150		0.600		0.314	0.314	>1.600	>1.600

Copper Layers - Copper to Copper Clearances - Original

File	Pos.	Copper to Copper Clr.				
		Overall	Pad to Pad	Pad to Track	Track to Track	Trace to Trace
		mm	mm	mm	mm	mm
top	1	0.235	0.309	0.235	0.341	0.341
bot	2	0.450	0.450	>0.500	>0.500	>0.500

Copper Areas - Original








Side	Total	Free of				Edge Connectors		
		Solder Mask (as supplied)	Solder Mask (open vias)	Gold Mask	Silver Mask	Fingers	Finger Size	Total Area
	dm ²	dm ²	dm ²	dm ²	dm ²		mm x mm	dm ²
Top (incl. 1/2 plated holes and routs)	0.0911	0.0321	0.0321					
Bottom (incl. 1/2 plated holes and routs)	0.0094	0.0094	0.0094					
Total (incl. plated holes and routs)	0.1005	0.0415	0.0415			0		
Plated holes and routs	0.0106	0.0106	0.0106					
Top (without plated holes and routs)	0.0858	0.0268	0.0268					
Bottom (without plated holes and routs)	0.0041	0.0041	0.0041					
Total (without plated holes and routs)	0.0899	0.0309	0.0309					

Drill Tools - Original



File	Tool Nr.	Span	Type	Function	Method	Filled Via	Counter	Dia.	Tol. -	Tol. +	Holes in PCB	Routs in PCB	Double Hits	Predrill Hits
								mm	mm	mm				
pth	10	1-2	PTH	comp.	mech.	unknown	unknown	2.700	0.000	0.000	3	0	0	0
pth_1	10	1-2	PTH	comp.	mech.	unknown	unknown	2.000	0.000	0.000	4	0	0	0
pth_1	11	1-2	PTH	comp.	mech.	unknown	unknown	2.500	0.000	0.000	2	0	0	0

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Drill Tools - Drill vs Copper - Original

File	Tool Nr.	Span	Type	Function	Method	Dia.	Ring on Outer	Ring on Inner	Min. Pad Size	Via in Pad	Plated to Copper Clr. 			
											!Min.Clr .Overall !	!Min.Clr .toPad!	!Min.Clr .toTrac e!	!Min.Clr .toRegi on!
						mm	mm	mm	mm		mm	mm	mm	mm
pth	10	1-2	PTH	comp.	mech.	2.700	>0.800		> 4.300		>0.800	>0.800	>0.800	>0.800
pth_1	10	1-2	PTH	comp.	mech.	2.000	0.150		2.300		0.447	0.459	0.447	>0.800
pth_1	11	1-2	PTH	comp.	mech.	2.500	0.150		2.800		0.600	0.600	0.654	>0.800

Sequences - Original

Span	Type	Tools	Min. End Dia.	Max. End Dia.	Holes	Ring on Outer	Ring on Inner	Hole to Copper Clr.	Hole to Hole Clr., within Seq.		Overlappi ng Holes, within Seq.	Hole to Hole Clr., between Seqs		Hole to Outline Clr.	Slot to Outline Clr.
									Any Net	Diff. Net		Any Net	Diff. Net		
			mm	mm		mm	mm	mm	mm	mm		mm	mm	mm	mm
1-2	PTH	3	2.000	2.700	9	0.150		0.447	0.750	0.750	No	>0.800	>0.800	1.314	>6.400
All	All	3	2.000	2.700	9	0.150		0.447	0.750	0.750	No	>0.800	>0.800	1.314	>6.400

Rout Tools - Original

File	Tool Nr.	Type	Tool Dia.	End Dia.	Rout Length	Nibble Count
			mm	mm	mm	














Routed Holes - Original

File	Hole Nr.	Instances	X Size	Y Size	Rout Length	Nibble Count
			mm	mm	mm	

Sequences Analysis - Original











File	Pos.	Stacked Vias	Overlap ped Vias	Via Plug Clr.	Top Tool			Bottom Tool		
					Top Drill File	Tool Nr.	Dia.	Bottom Drill File	Tool Nr.	Dia.
				mm			mm			mm

SMD (Incl. BGA) - Original

	SMD (Incl. BGA)				SMD (Excl. BGA)	BGA				
Side	Pads	Min. Pad	Pitch of Min. Pad	Solder Mask Defined Pads	Pads	Pads	Min. Pad	Min. Pitch	All Tracks Centered	Drilled Pads
		mm	mm				mm	mm		
Top	66	0.480	2.770	0	66	0				
Bottom	0			0	0	0				
Both	66			0	66	0				

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Solder Mask - Original

Side	Mask to Mask Clr.	Web	Ring on Cu Defined Pads	Ring on SM Defined Pads	Mask to Copper Clr.	Mask Opening	Fully Covered Via Holes	Partly Covered Via Holes	One Side Covered Vias 	Both Sides Covered Vias 	No Side Covered Vias 
	mm	mm	mm	mm	mm	mm					
Top	>0.250	>0.250	>0.250	>0.250	0.000	0.480	No	No			
Bottom	>0.250	>0.250	>0.250	>0.250	>0.250	2.300	No	No			
Both	>0.250	>0.250	>0.250		0.000	0.480	No	No	No	No	No

Carbon Masks - Original

File	Position	Carbon Width	Carbon to Carbon Clr.	Clr. to Plated Hole	Clr. to Outline	Layer Area	
		mm	mm	mm	mm	dm ²	%

Peeloff Masks - Original

File	Position	Min. Peelable Width	Peelable to Peelable Clr.	Clr. to Plated Hole	Clr. to Outline	Layer Area	
		mm	mm	mm	mm	dm ²	%

Legend Layers - Original

File	Position	Legend Width	Legend to Legend Clr.	Legend to (Comp/SMD/BGA) Pad Clr.	Layer Area	
		mm	mm	mm	dm ²	%
silk-top	top	0.100	0.009	0.049	0.0126	8

Gold Layers - Original

File	Position	Gold to Gold Clr.	Clr. to Outline	Layer Area	
		mm	mm	dm ²	%







Heatsink Layers - Original

File	Position	Heatsink to Heatsink Clr.	Clr. to Outline	Layer Area	
		mm	mm	dm ²	%

Scoring - Minimum Clearance - Original

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Bare Board Test - Original

Side	Testable Points (TPs)	Max. TP Density	SMD Pads	Min. SMD Pad	Pitch of Min. SMD Pad	Edge Connector Fingers	Number of Nets
		TP/dm ²		mm	mm		
Top	75	809	66	0.480	2.770	0	
Bottom	9	154	0			0	
Both	84	809	66			0	28

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DFM Classes - Original

			Standard						Advanced		
			1	2	3	4	5	6	7	8	9
Track & Gap	Min Clearance (Track-Track / Track-Pad / Pad-Pad)	0.235	0.300	0.250	0.200	0.150	0.130	0.120	0.100	0.075	0.060
	Min Track Width / Thermal Gap	0.250	0.300	0.250	0.200	0.150	0.130	0.120	0.100	0.075	0.060
Ring for IPC Class 2	Outer Min Layer Annular Ring	0.150	0.250	0.220	0.200	0.150	0.130	0.120	0.100	0.075	0.060
	Inner Min Layer Annular Ring		0.250	0.220	0.200	0.150	0.130	0.120	0.100	0.075	0.060
Aspect Ratio	Max Aspect Ratio for Plated Hole	0.800	8.000	8.000	8.000	8.000	10.000	10.000	10.000	10.000	10.000
Drill - Cu	Distance PTH to PTH	0.750	0.600	0.500	0.400	0.350	0.300	0.300	0.275	0.250	0.230
Cu Thickness	Max Cu Thickness that can be etched		0.175	0.140	0.105	0.070	0.070	0.035	0.035	0.035	0.017
Solder Mask	Solder Mask Annular Ring	0.000	0.100	0.075	0.050	0.050	0.050	0.050	0.040	0.030	0.010
	Solder Mask SolderWeb		0.150	0.125	0.100	0.100	0.100	0.100	0.080	0.075	0.075

Input Remarks - Original

Gerber import: Invalid coincident draw, continuing without cleanup 'copper-top.pho'
Layer does not contain any image data (demoted to 'empty') 'silkscreen-bottom_pho'
Layer does not contain any image data (demoted to 'empty') 'stencil-bottom_pho'
Gerber Job File import: DISCREPANCY: Extra top layers mismatch between Gerber Job File and current job stackup.
Gerber Job File import: OMITTED: \$.MaterialStackup[6] not added to layer attributes because corresponding layer could not be found.

Customer and Job Identification - Original

Customer	
Customer	Contact Person
Email	

Customer and Job Identification - Original

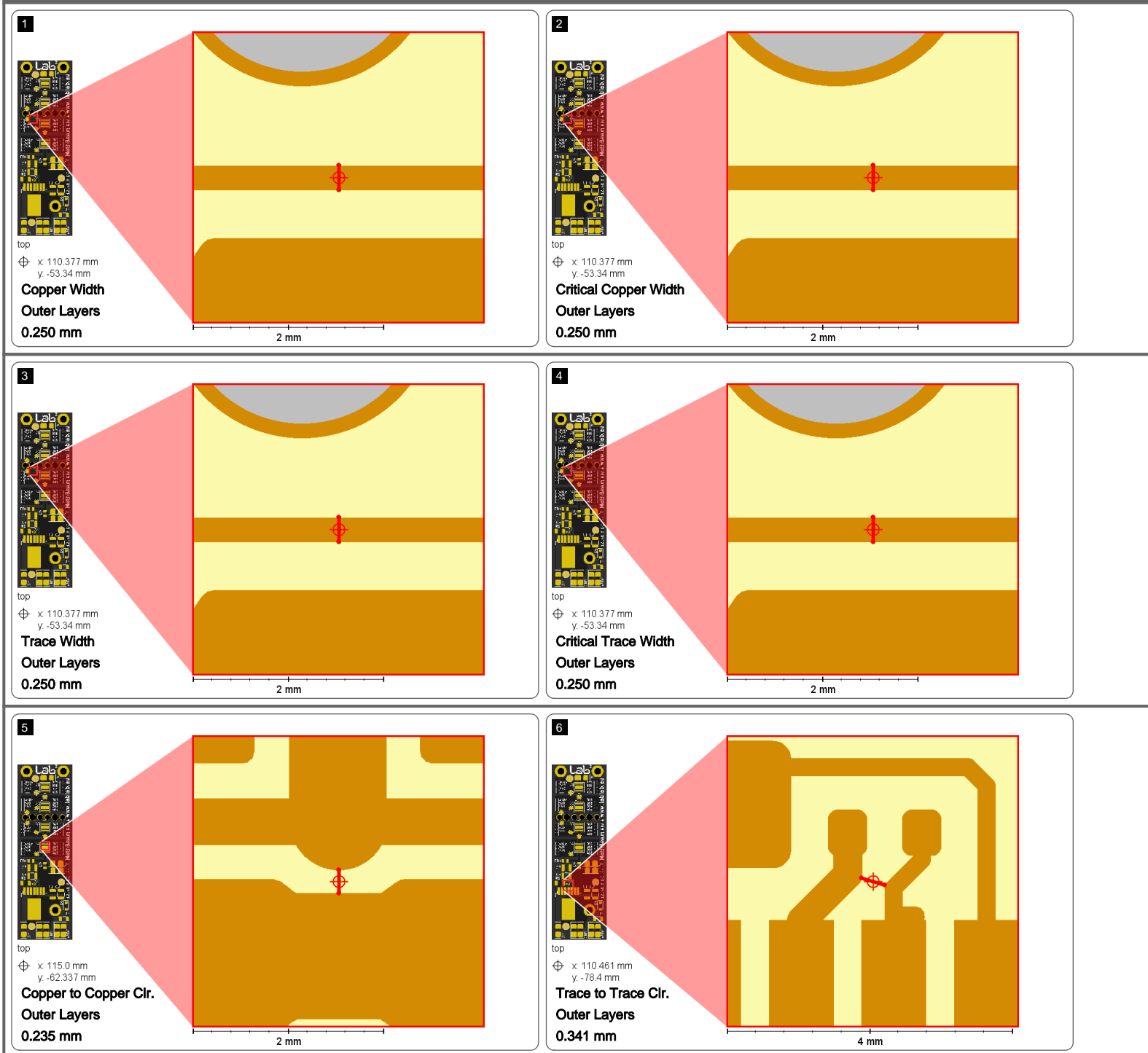
Job	
Article Id	Board Id
DPMX Output Path	CH

Comments - Original

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Summary Minimum Design Characteristics - Locations - Original



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